ABSTRACT OF THE DISCLOSURE

The present invention provides an electroplating device including an anode inserted through and disposed in a hole provided in a work and communicating with the outside, and a member for rotating the work about its center axis and supplying a plating electric current to the work. The present invention also provides an electroplating device including an anode inserted through and disposed in a hole provided in a work and communicating with the outside, a member for rotating the work about its center axis, and a member for supplying a plating electric current to the work. Further, the present invention provides an electroplating device including an anode inserted through and disposed in a hole provided in a work and communicating with the outside, and a means for allowing a plating solution in the hole in the work to flow. Thus, a uniform plated film can be formed on both of the outer and inner surfaces of the work having the hole communicating with the outside such as a ring-shaped work, of which a ring-shaped bonded magnet is representative, by using the electroplating device.